



100% Material Declaration Data Sheet VO8

PK174 (v1.1) February 20, 2007

Material Declaration Data Sheet

Average Weight: 0.524 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.0127	2.43%
	Silicon	7440-21-3	99.00		0.0126	
	Al	7429-90-5	1.00		0.0001	
Die Attach Material					0.0028	0.54%
	Epoxy resin(EP)	29690-82-2	25.00		0.0007	
	Silver	7440-22-4	75.00		0.0021	
Encapsulation					0.3443	65.76%
	Resin	29690-82-2	26.00		0.0913	
	SiO2 Filler	60676-86-0	74.00		0.253	
Leadframe					0.1552	29.65%
	Iron	7439-89-6	58.00		0.090	
	Nickel	7440-02-0	42.00		0.0652	
Bond Wire					0.0007	0.13%
	Gold	7440-57-5	100.00		0.0007	
Ext. Plating					0.0078	1.49%
	Tin	7440-31-5	85.00		0.0066	
	Lead	7439-92-1	15.00		0.0012	

PK174 (v1.1) February 20, 2007

www.xilinx.com

1

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
9/25/06	1.0	Initial release.
2/20/07	1.1	Updated component descriptions and weights.